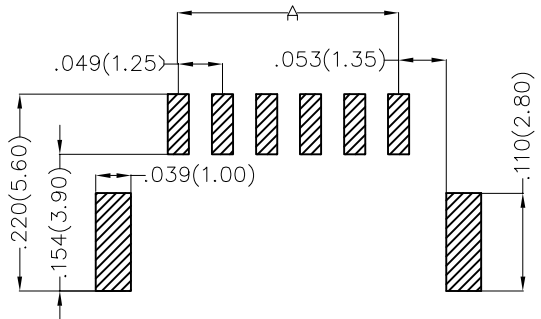
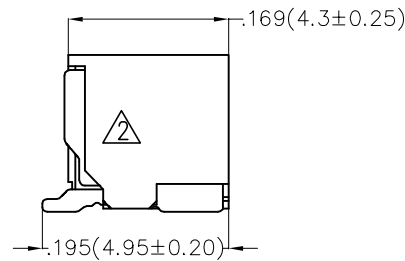
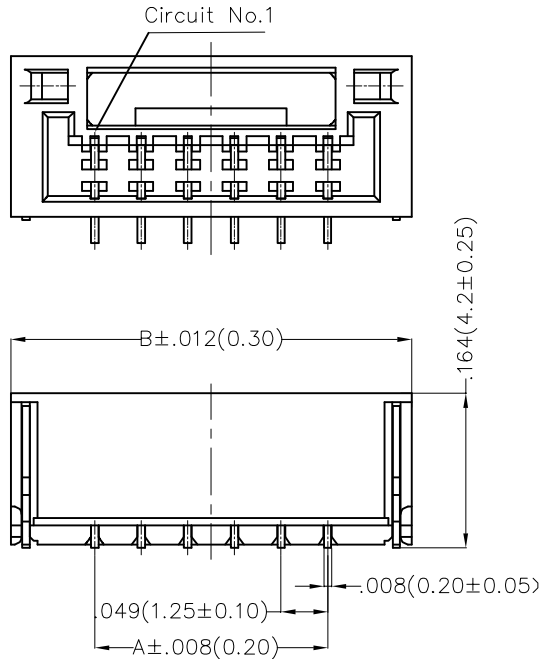


1 2 3 4 5 6 7 8

| REV | LOCATIONS | DESCRIPTION | DATE | REVISER | APPD |
|-----|-----------|------------------------------|-----------|---------|--------|
| 1 | △ | Material-Resin change | 26/APR/20 | KATE | CHERRY |
| 2 | △ | Update view structure | 18/AUG/22 | MATT | CHERRY |
| 3 | | Add Circuit Size Layout page | 05/JUN/25 | MATT | LEO |



Recommended P.C.Board Layout
Tolerances: ±.002(±0.05)

Electrical
 Current Rating: 1.0A AC(rms)/DC
 Voltage Rating: 50V AC(rms)/DC
 Contact Resistance: 30 mΩ Max
 Insulation Resistance: 100 MΩ MIN
 Withstanding Voltage: 100V AC r.m.s
 Temperature Range-Operating: -25°C~+85°C

Material and Plating
 Housing: PA9T(UL 94V-0) △
 Contact Pin: Phosphor Bronze/ Tin plated
 Solder Tab: Phosphor Bronze/ Tin plated
 Mates With: FHG12507 Series

| Circuits (n) | Part No. | Dimensions(in/mm) | |
|--------------|--------------------|-------------------|-------------|
| | | A | B |
| 2 | FWF12513-S02S24W5M | .049(1.25) | .226(5.75) |
| 3 | FWF12513-S03S24W5M | .098(2.50) | .276(7.00) |
| 4 | FWF12513-S04S24W5M | .147(3.75) | .325(8.25) |
| 5 | FWF12513-S05S24W5M | .197(5.00) | .374(9.50) |
| 6 | FWF12513-S06S24W5M | .246(6.25) | .423(10.75) |
| 7 | FWF12513-S07S24W5M | .295(7.50) | .472(12.00) |
| 8 | FWF12513-S08S24W5M | .344(8.75) | .522(13.25) |
| 9 | FWF12513-S09S24W5M | .394(10.00) | .571(14.50) |
| 10 | FWF12513-S10S24W5M | .443(11.25) | .620(15.75) |
| 11 | FWF12513-S11S24W5M | .492(12.50) | .669(17.00) |
| 12 | FWF12513-S12S24W5M | .541(13.75) | .719(18.25) |
| 13 | FWF12513-S13S24W5M | .591(15.00) | .768(19.50) |
| 14 | FWF12513-S14S24W5M | .640(16.25) | .817(20.75) |
| 15 | FWF12513-S15S24W5M | .689(17.50) | .866(22.00) |

Ordering Information

FWF 125 13 - S XX S 2 4 W5 M
 1 2 3 4 5 6 7 8 9 10

| | | | | | |
|---------------------------|------------------------------------|-----------------------------|------------------------------|------------------|----------------------------------|
| 1 Category FWF-Wafer | 2 Series Number 125-Pitch1.25mm | 3 Distinction No. 13 | 4 Row Option S-Single Row | 5 Circuits XX | 6 Entry Angle S-180° Vertical |
| 7 Plating 2-Tin Plated | 8 Material-Resin 4-PA9T △ | 9 Color-Resin W5-Natural | 10 Packaging M-Reel | | |

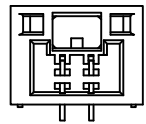
| | | | | | | | |
|------------------------|---------------------------------------|-------------------------------------|---------------------|----------------------|--------------------------------|--|-------------------------------------|
| THIRD ANGLE PROJECTION | GENERAL TOLERANCES (UNLESS SPECIFIED) | | APPROVE BY FRANK | DATE 8/JUL/13 | PART NO. FWF12513-SXXS24W5M | ITEM NO. FWF12513 | Building Technology Cornerstone |
| | DESIGN UNITS Inch (metric) | X.±.012(0.30) X.X±.008(0.20) | X'±5' .X'±2' | CHECKED BY CHERRY | DATE 8/JUL/13 | TITLE Wire to Board (Wafer) Pitch 1.25mm 180° Vertical (SMT) | |
| SCALE 5:1 | SIZE A4 | X.XX±.006(0.15) X.XXX±.004(0.10) | .XX±1' .XXX±0.5' | DRAWN BY KEVIN | DATE 8/JUL/13 | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | |

1 2 3 4 5 6 7 8

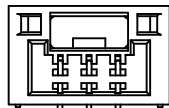
1 2 3 4 5 6 7 8

| REV | LOCATIONS | DESCRIPTION | DATE | REVISER | APPD |
|-----|-----------|-------------|------|---------|------|
| | | | | | |

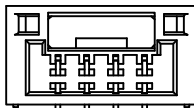
Circuit Size Layout



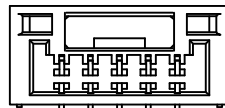
2 Circuits



3 Circuits



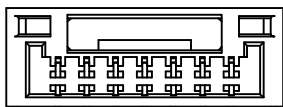
4 Circuits



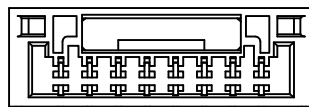
5 Circuits



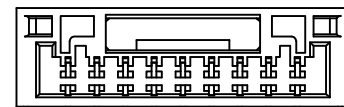
6 Circuits



7 Circuits



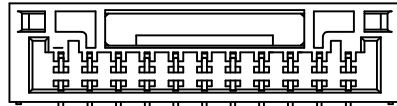
8 Circuits



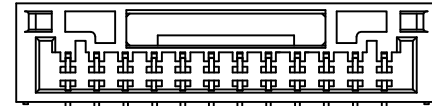
9 Circuits



10 Circuits



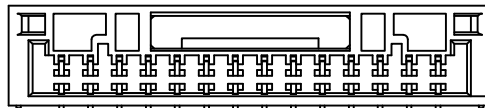
11 Circuits



12 Circuits



13 Circuits



14 Circuits



15 Circuits

| | | | | | | | | |
|-------------------------------|--|-----------------------------|------------------------------------|---------------------------|---|---|--|----------------------------|
| <p>THIRD ANGLE PROJECTION</p> | <p>GENERAL TOLERANCES (UNLESS SPECIFIED)</p> | | <p>APPROVE BY FRANK</p> | <p>DATE 8/JUL/13</p> | <p>PART NO. FWF12513-SXXS24W5M</p> | <p>ITEM NO. FWF12513</p> | <p>Building Technology Cornerstone</p> | |
| | <p>DESIGN UNITS Inch (metric)</p> | <p>X.±.012(0.30) X'.±5'</p> | <p>CHECKED BY CHERRY</p> | <p>DATE 8/JUL/13</p> | <p>TITLE Wire to Board (Wafer) Pitch 1.25mm 180° Vertical (SMT)</p> | | | <p>REV 3 SHEET NO. 2/2</p> |
| | <p>SCALE 5:1</p> | <p>SIZE A4</p> | <p>X.XX±.006(0.15) .XX'±1"</p> | <p>DRAWN BY KEVIN</p> | <p>DATE 8/JUL/13</p> | <p>THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION</p> | | |
| | | | <p>X.XXX±.004(0.10) .XXX'±0.5'</p> | | | | | |

1 2 3 4 5 6 7 8